

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6958935

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WU-HAN LIU	09/10/2021
YI-LIANG LIAO	09/10/2021
TAI-SHENG CHEN	09/10/2021
WEI-TIEN HSIAO	09/10/2021
CHANG-CHIH HSU	09/10/2021
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17493863
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SIGNATURE:	/Belinda Lee/
DATE SIGNED:	10/08/2021
Total Attachments: 2	
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ASSIGNMENT

WHEREAS,

1.Wu-Han Liu
3.Tai-Sheng Chen
5.Chang-Chih Hsu

2.Yi-Liang Liao
4.Wei-Tien Hsiao

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **COMPOSITE STRUCTURE WITH ALUMINUM-BASED ALLOY LAYER
CONTAINING BORON CARBIDE AND MANUFACTURING METHOD
THEREOF**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. Industrial Technology Research Institute
of 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 310401,
Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Wu-Han Liu Date: 2021/9/10

Sole or First Joint Inventor: **Wu-Han Liu**

Signature: Yi-Liang Liao Date: 2021/9/10

Second Joint Inventor (if any): **Yi-Liang Liao**

Signature: Tai-Sheng Chen Date: 2021/9/10

Third Joint Inventor (if any): **Tai-Sheng Chen**

Signature: Wei-Tien Hsiao Date: 2021/09/10

Fourth Joint Inventor (if any): **Wei-Tien Hsiao**

Signature: Chang-chih Hsu Date: 2021/09/10

Fifth Joint Inventor (if any): **Chang-Chih Hsu**